Usages of Memristors

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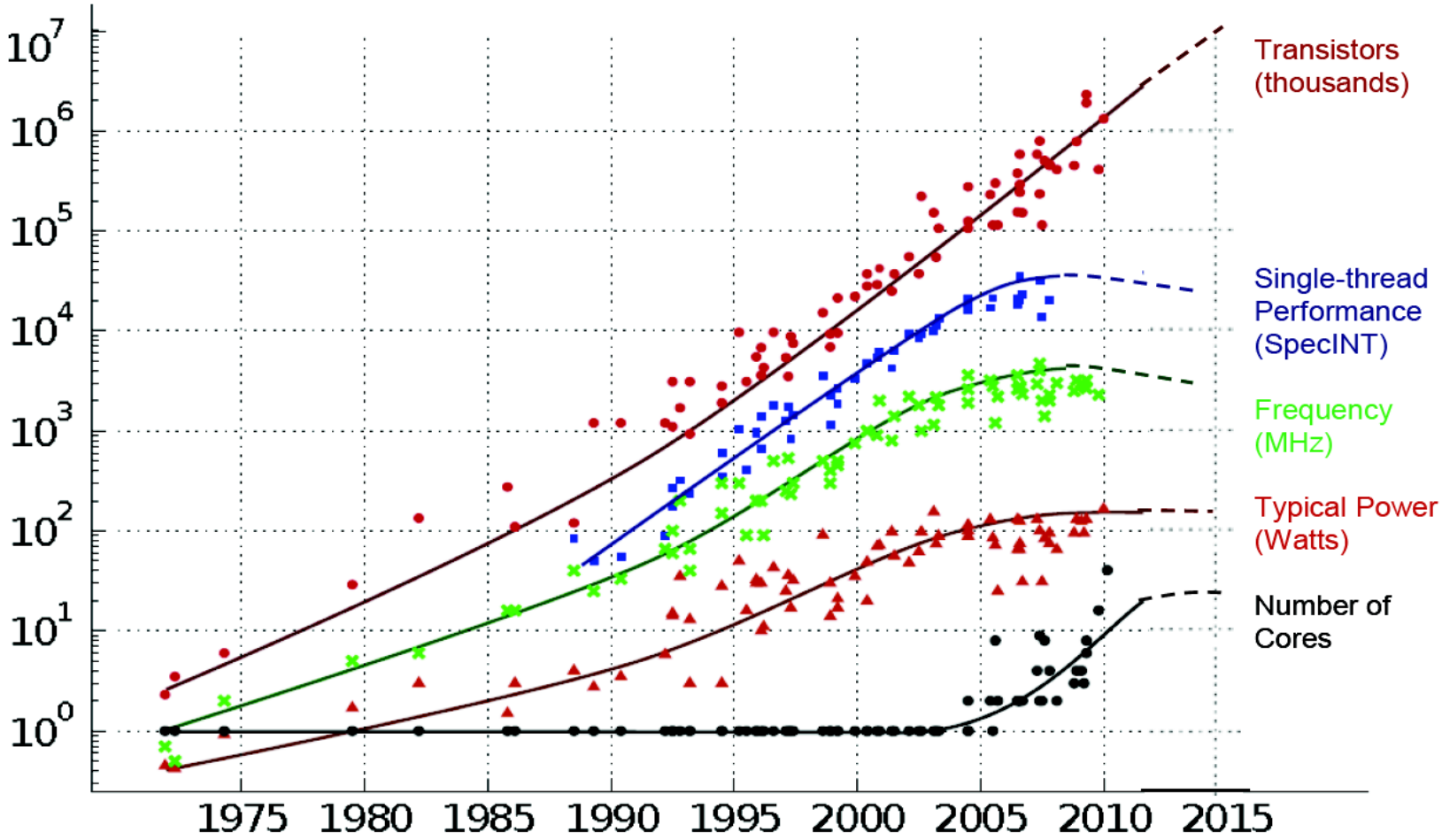
35 YEARS OF MICROPROCESSOR TREND DATA

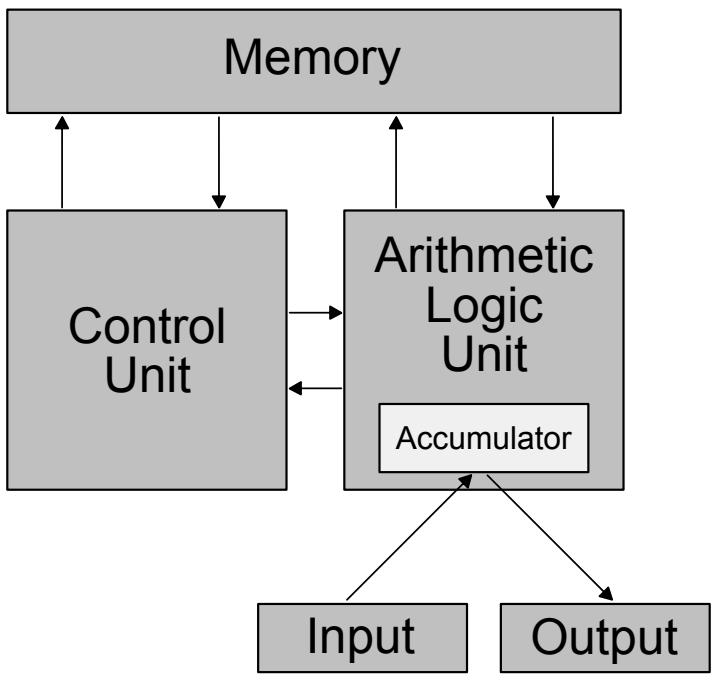


Original data collected and plotted by M. Horowitz, F. Labonte, O. Shacham, K. Olukotun, L. Hammond and C. Batten

Von Neumann Architecture

Current computing architecture:

- Memory and processing are physically separate
- Transmission of information is becoming a bottleneck



Main memory and Processor

Leakage is currently one of the main factors limiting increased computer processor performance

Main Memory:

- DRAM: Dynamic Random Access Memory
- Capacitors leak energy
- Need to be continually reset

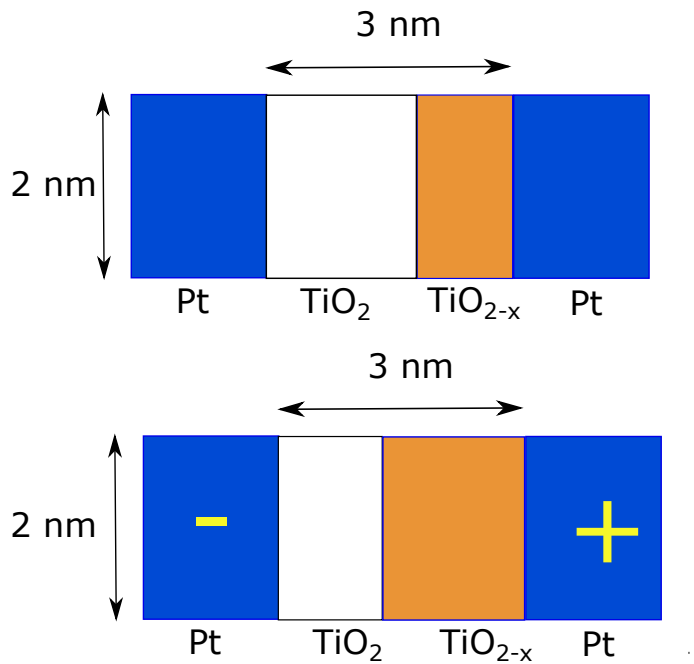
Processor:

- Transistors
- Need a constant current to maintain state
- Has SRAM caches (Static Random Access Memory)

Outline

The Memristor

- mem: memory, -ristor: resistor
- Non-volatile, memory and switching device
- Originally used resistive TiO_2 and conductive TiO_{2-x}
- Applying current alters the state
- In the figure: nm (nano meters), Pt (platinum electrodes)

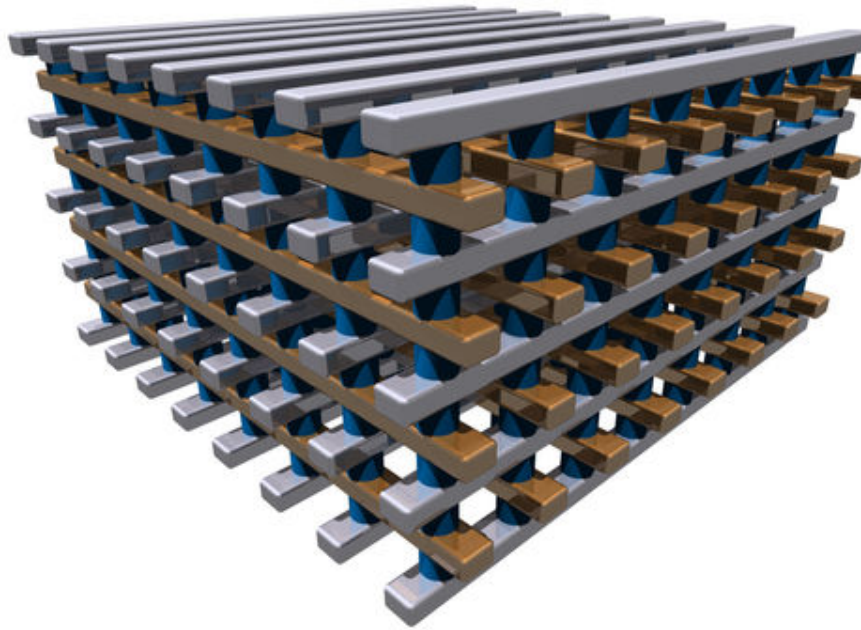


History Abridged

- Originally theorized in 1971 by L. Chua
- Physical memristor construction published in 2008 by S. Williams et al.
- Long story short: the theoretical and 2008 memristor are not equivalent (S. Vongehr and X. Meng)
- More proper to call the memristor a resistance switching device
- Despite this, the memristor is a promising device

Crossbar Array

- Scalable, layerable
- Potential to store Petabits of memory within a cm^3
- Can be mass produced using current techniques



Other Potential Non-volatiles

STT-RAM

- Spin transfer torque random access memory
- New implementation of magnetoresistive RAM
- Requires a significant current to alter state

PCM

- Phase change memory
- Alters state by melting into either a conductive or resistive state

Comparison to other prospective memories

- Retention: How long the device will retain its state after a write
- Endurance: How many writes before the device fails
- 3D capability: Whether or not the device can be constructed in layers

	Memristor	PCM	STT-RAM	DRAM	Flash	HD
Chip area per bit (F^2)	4	8-16	14-64	6-8	4-8	
Energy per bit (pJ)	0.1-3	2-100	0.1-1	2-4	10^{1} – 10^{3}	10^{6} – 10^{7}
Read time (ns)	<10	20-70	10-30	10-50	25,000	5-8 X 10^{6}
Write time (ns)	20-30	50-500	13-95	10-50	200,000	5-8 X 10^{6}
Retention	10 years	<10 years	Weeks	< Second	~10 years	~10 years
Endurance (cycles)	10^{12}	10^{7} – 10^{8}	10^{15}	10^{17}	10^{3} – 10^{6}	10^{15}
3D capability	Yes	No	No	No	Yes	

Newer Implementation

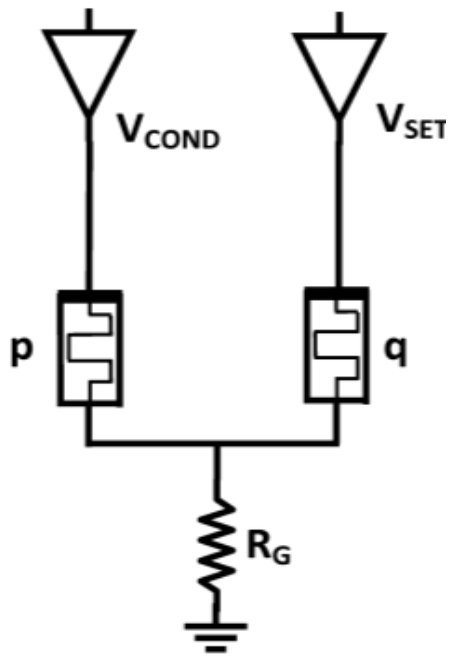
Tantalum-Oxide based memristor: S. Williams et al.

- Switching times from 105 to 120 pico seconds
- Associated energies: 1.9 and 5.8 pico joules
- The device in question was 2 micro meters in length

Material Implication Logic

IMP: $(p \rightarrow q) \vdash (\neg p \vee q)$

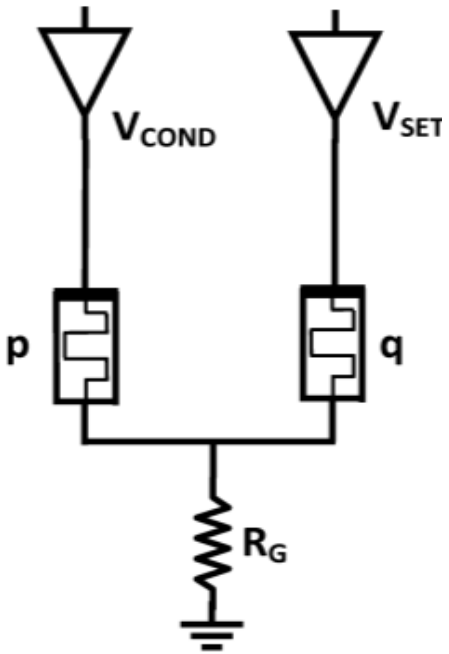
- Kvatinsky et al.
- Like the nand gate, the imply gate implements any boolean function
- Memristors P and Q with initial values p and q
- Memristor Q is treated as the output
- V_{cond} and V_{set} are voltages where $(|V_{\text{cond}}| < |V_{\text{set}}|)$
- R_G has a resistance between R_{Off} and R_{On}



Material Implication Logic

IMP

- Apply voltage V_{cond} to P and V_{set} to Q



Material Implication Logic

IMP

- If $p = q = 0$ (high resistance)
- Voltage on Q is approximately V_{set}
- Q is switched to 1.

Case	p	q	p→q
1	0	0	1
2	0	1	1
3	1	0	0
4	1	1	1

Material Implication Logic

IMP

- If p = 0 and q = 1,
- the state of Q is unchanged

Case	p	q	p→q
1	0	0	1
2	0	1	1
3	1	0	0
4	1	1	1

Material Implication Logic

IMP

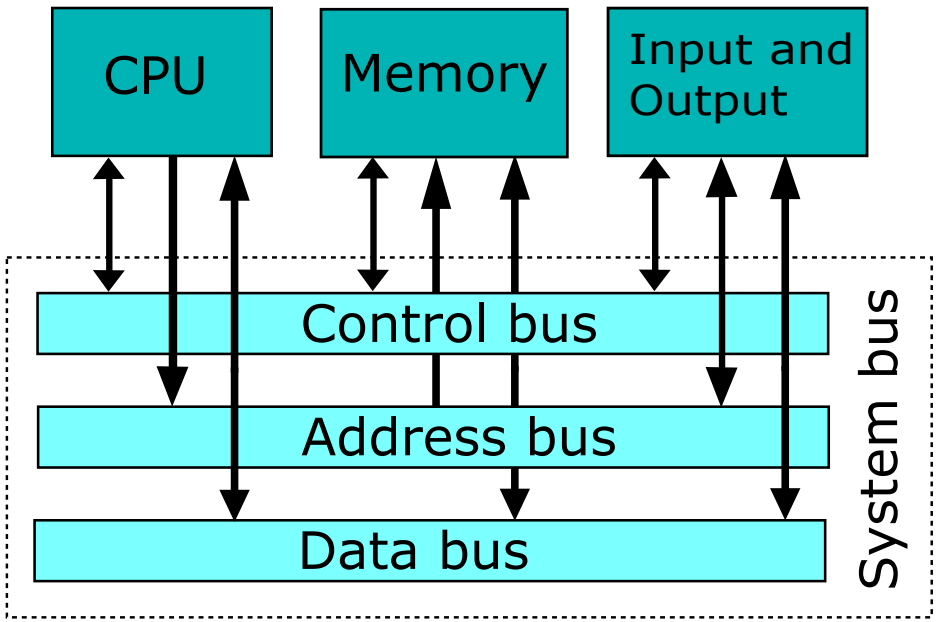
- If p $= 1$ (low resistance)
- Voltage on Q is $V_{\text{set}} - V_{\text{cond}}$
- Voltage on Q is small enough that the state of Q is unchanged.

Case	p	q	p→q
1	0	0	1
2	0	1	1
3	1	0	0
4	1	1	1

Von Neumann Bottleneck

Issues:

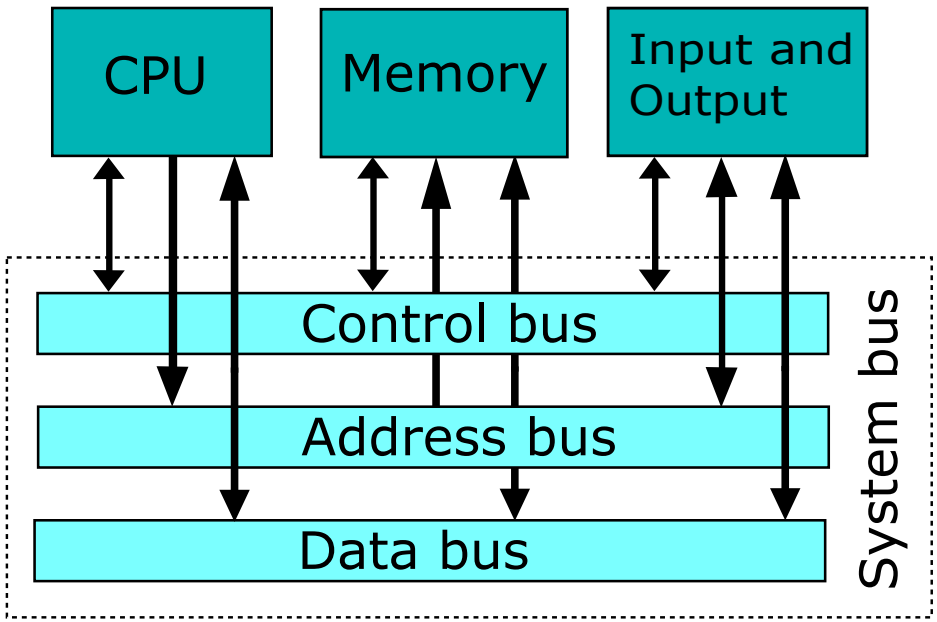
- Information between processor and main memory is shared by a system bus
- The bus can only access the processor or memory, one at a time



Von Neumann Bottleneck

Issues:

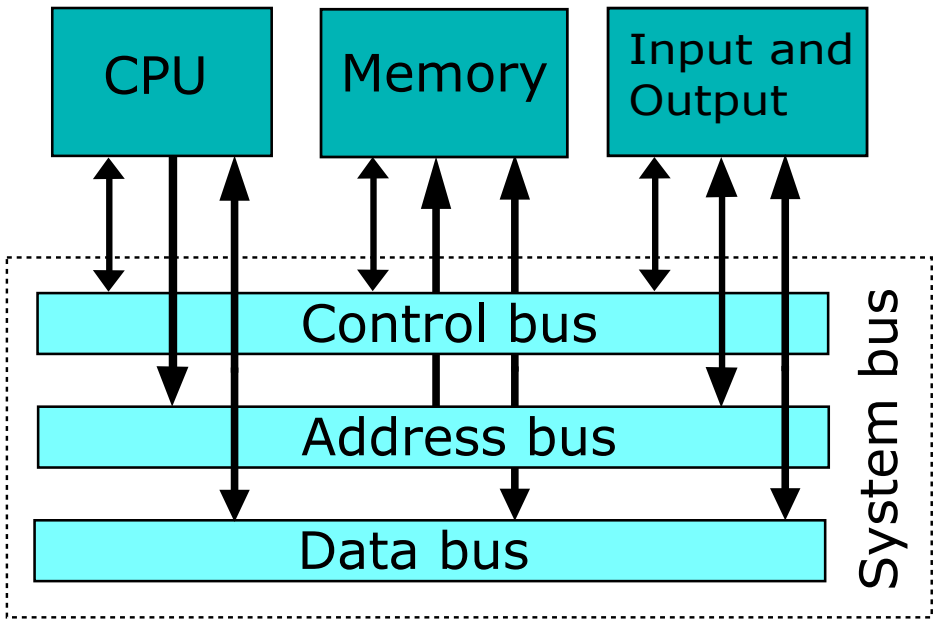
- Processor will be idle while the bus is getting information from main memory
- Study from 1996 found that 3 out of 4 CPU cycles spent waiting for memory
- Processor processing and main memory transfer rate are more than the data transfer rate of the bus



Von Neumann Bottleneck

Some current mitigations:

- SRAM based caches between the CPU and main memory
- Providing the CPU a limited stack or scratch-pad memory



Computation in Memory Architecture

Computation in Memory (CIM) as propsed by Hamdioui et al. aims to combine main memory and processing into a single crossbar array. The memory/computing crossbar array allows for:

- Massive parallelism
- Little to no power leakage (no longer accessing SRAM caches)
- Performance improvement at lower energy and area (no communication bottleneck)

Specifics of Architectures Compared

Von Neumann architecture:

- 22nm multi-core implementation
- 64 clusters
- Each cluster has 32 ALUs that share an 8KB L1 cache

Computation in Memory architecture:

- 5nm memristor crossbar
- Crossbar size is equal to total cache size of the VN architecture

Data Sets to Compare VN vs CIM

DNA comparison:

- A sorted index of reference DNA is created in order to identify the locations of matches or mismatches in another sequence.
- Comparing 200 GB of DNA to a 3 GB healthy reference.

10^6 parallel additions

Results

- Energy-delay / operations: Energy consumed per operation (joules)
- Computing efficiency: Number of operations per energy (n/J)
- Performance Area: Operations per area

Metric	Archit.	DNA Sequencing	10^6 additions
Energy-delay/ operations	VN	2.02e-03	1.50e-18
	CIM	2.34e-06	9.26e-21
Computing efficiency	VN	4.11e+01	6.52e+09
	CIM	3.70e+04	3.91e+12
Performance area	VN	5.73e+06	5.11e+09
	CIM	8.28e+09	4.92e+12

The Good

- On their own memristors seem to be a very competitive memory
- They are scalable and potentially cheap to manufacture
- Computation in memory architecture has excellent potential

The Bad

- Completely new logic operations could require significant changes to software
- Combined with a complete overhaul of the architecture, CIM could take some time to be developed

Discussion

Questions?

References

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